

AutoInspector Series - Ultra 850G

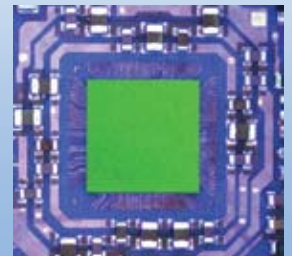
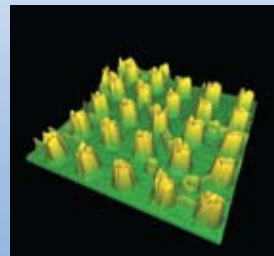
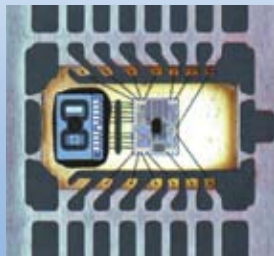
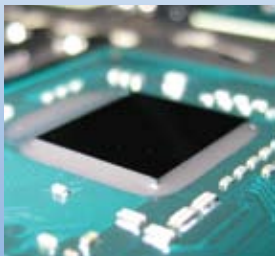
The Ultra 850G modular AOI solution is capable of a range of electro-optic solutions including flying color, UV lighting and true color. Camera FOVs are scalable to produce a pixel size of 3-25 microns. In addition a range of flexible material handling solutions including single and dual lane are available to process pcb assemblies, JEDEC trays and metal carriers.

Configurable electro-optics solutions provide performance inspection capabilities for:

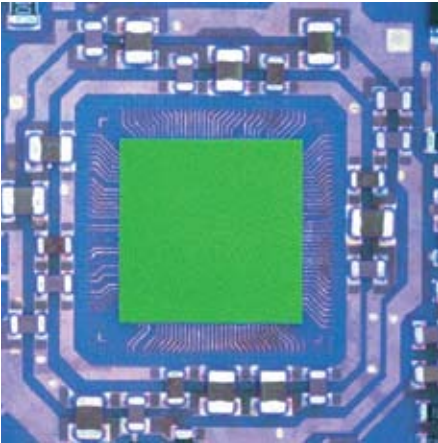
- C4 and SMT Integrated Inspection
- High Accuracy Die Placement Measurement
- Surface Finish and Scratches
- 2D Flux
- Epoxy Spread, Pre and Post Cure
- Wire bond with Loop Height
- Glues and Sealants
- 3D Paste and BGA
- SMT Pre and Post Reflow
- LEDs



Discuss your micro electronics inspection application with Machine Vision Products, Inc and discover your solution.



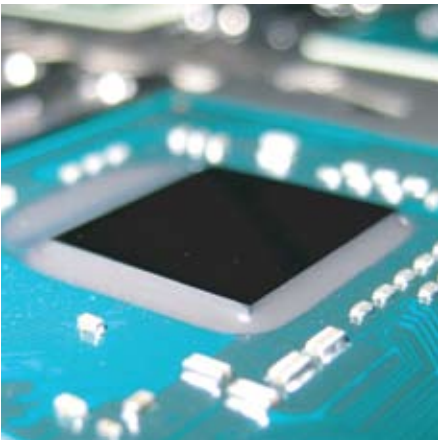
the vision to improve your process



High Accuracy C4 Assembly Inspection

- In-line High Speed Positional Accuracy of C4 Die Placement
X, Y and Rotation, Post and Pre Reflow
- Die Damage
Cracks, Contamination and Edge Quality
- Single and Multiple Die
- Hybrid C4 and SMT Component Inspection
- Single or Dual Lane Options
- Metal and JEDEC Carrier or Strip Material Handling

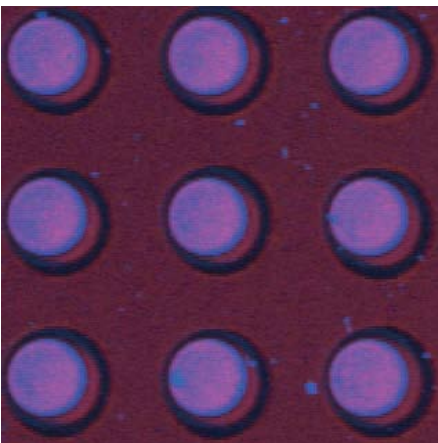
Applicable Models **MVP 850 XD** and **MVP 850 SD**



C4 Epoxy Underfill

- Epoxy Boundary (Flow and Spread)
- Epoxy Fillet (Quality and Defects)
- Excess Epoxy (Anywhere in the Inspection Area)
- Pre and Post Epoxy Cure
- Inline or Offline
- Single or Dual Lane Options
- Metal or JEDEC Carrier or Strip Material Handling

Applicable Models **MVP 850 XE** and **MVP 850 SE**



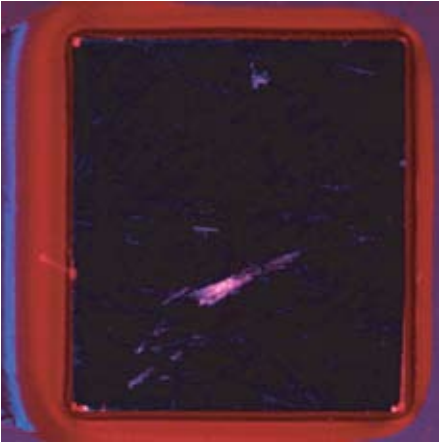
2D Flux Inspection without Florescent Additives

- Flux Boundary and Coverage (Flow and Spread)
- Flux Deposition Positional Accuracy
- Single or Dual Lane Options
- Metal or JEDEC Carrier or Strip Material Handling

Applicable Models **MVP 850 XF** and **MVP 850 SF**

Single Platform
Multiple Solutions

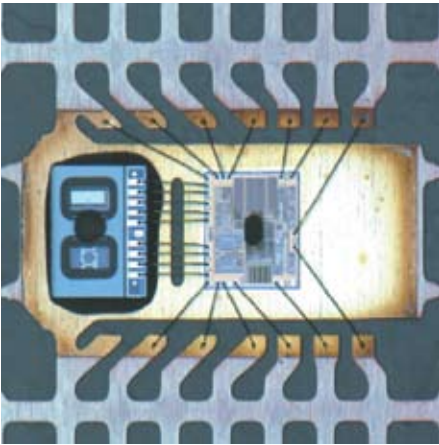
our
Vision
your Success



Surface Finish and Scratches

- Surface Damage such as Scratch, Exposed Circuitry
- Single or Dual Lane
- Metal or JEDEC Carrier, or Strip Material Handling

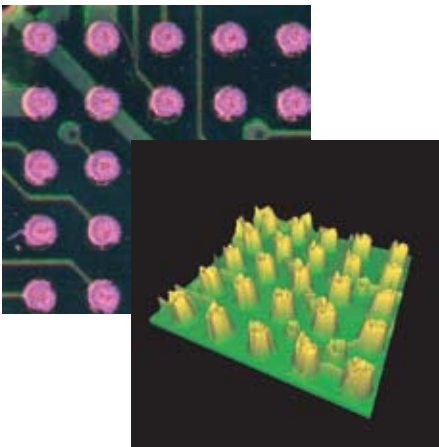
Applicable Models **MVP 850 XD** and **MVP 850 SD**



Wire Bond

- Loop Height
- Wire Tracing Conformity, Bent and Broken Wires
- Distance to Adjacent Wire, Straightness Tolerance
- Ball/Wedge Geometry
- Contamination
- SMT Assembly Defects
- Single or Dual Lane
- Metal or JEDEC Carrier, or Strip Material Handling

Applicable Models MVP 850 XD and MVP 850 SD



3D Paste

- In-line High Speed Inspection of Paste Deposition
 - Positional Accuracy
 - Volume
 - Height
- Single or Dual Lane
- Metal or JEDEC Carrier, or Strip Material Handling

Applicable Models **MVP 850 XP** and **MVP 850 SP**

Single Platform
Multiple Solutions



The Ultra 850G is the latest in a series of flexible, powerful and innovation driven solutions introduced by MVP, the leader in performance based AOI. With the flexibility to inspect a variety of micro-electronics processes, the modular nature of the Ultra 850G is an ideal fit for performance driven production environments.

Ultra 850G Technical Specifications

Inspection Speed	<ul style="list-style-type: none">• Acquisition Speed of 56 Megapixels per Second with a Single 4MP Camera• Up to 5400 Units Per Hour	Material Handling	<ul style="list-style-type: none">• SMEMA Interface• Flexible PLC Control• Auto Board Clamp for Precision Registration• Single and Dual Lane• Support for Metal Carriers and JEDEC Standard Trays• Support for Thin and Standard PCB processing
System Hardware	<ul style="list-style-type: none">• Granite-based Stage for High Measurement Accuracy• State-of-the-art Large Format Color Camera• Proprietary "On-the-fly" Camera Acquisition• Programmable Variable LED Strobe Lighting• Proprietary Multi-color Illumination• Field of View Resolution 3 - 25 Micron/Pixel• 0201 and 01005 Capable• Copy-exact, Inter-machine Capability	Physical Specification	<ul style="list-style-type: none">• Inspection Envelope 355 x 355mm (14 x 14")• Footprint 844 x 1066mm (33.25 x 42").• Height 1473mm (58")• Conveyor Length 850mm (33.46")• Power 220-240VAC 50/60Hz, 10 Amperes.• Air 60 PSI, 1CFM• Weight 680kgs (1500 lbs)
System Software	<ul style="list-style-type: none">• CAD-driven, Library-based Programming Software• Proven High Performance, Adaptable Algorithms with Highest Detectability and Lowest PPM False Accept and False Reject Rates• Full Network Integration (TCP/IP, NFS Protocol)• Off-line or In-line Defect Review Capability• Defect Image Archive Capability• Real-time SPC Package• Report Generation Utilities for Production Inspection Measurements• Inspection Program Change Tracking• On-the-fly Unit Level and Carrier Tracking with 2D Matrix Reader• 5th Generation Proven Inspection Software• Multi-pass Technology, Adjustable Lighting Intensity• Multi-substrate Step and Repeat Programming and Inspection Capability	System Configurations	<ul style="list-style-type: none">• MVP 850 XD and SD C4 + SMT Integrated Assembly Inspection Surface Inspection Wirebond• MVP 850 XE and SE C4 Epoxy Underfill with Surface Inspection and Component Inspection• MVP 850 XF and SF 2D Flux Inspection• MVP 850 XP and SP 3D Paste Inspection
		Options	<ul style="list-style-type: none">• Grayscale Acquisition• CAD Translation Software• Offline Programming Capability• MVP Dynamic Process Control• Ceramic Process Material Handling

Worldwide Headquarters
Carlsbad, California USA
800.260.4MVP or 760.438.1138
sales@visionpro.com

European Headquarters
Fife, Scotland UK
+44 (0) 1383 629960
salesuk@visionpro.com

Asia-Pacific Headquarters
Shanghai, P.R.C.
+86 21 5046 2330
salesasia@visionpro.com

our
Vision
your Success